

UNCONTROLLED DOCUMENT

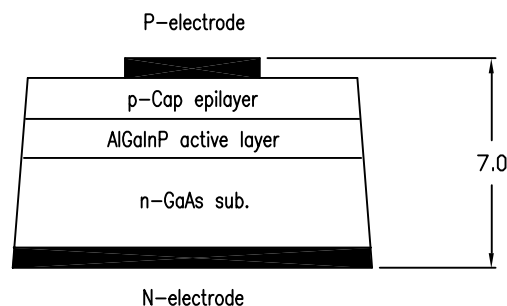
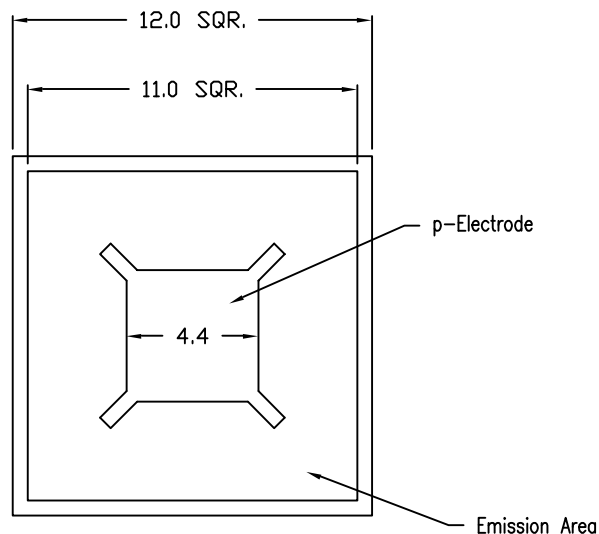
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PART NUMBER

REV.

SSD-LX012E590FGPU

PRELIMINARY IN P/N DIR



ELECTRO-OPTICAL CHARACTERISTICS:

PARAMETER	SYMBOL	TEST COND	MIN	TYP	MAX	UNITS
FORWARD VOLTAGE	V_{f2}	$I_f=20\text{mA}$		1.95	2.4	V
REVERSE CURRENT	I_r	$V_r=5\text{V}$			10	μA
PEAK WAVELENGTH	λ_p	$I_f=20\text{mA}$		590		nm
DOMINANT WAVELENGTH ⁽¹⁾	λ_d	$I_f=20\text{mA}$	576	586	596	nm
SPECTRA HALF-WIDTH	$\Delta\lambda$	$I_f=20\text{mA}$		20		nm
LUMINOUS INTENSITY ⁽²⁾	I_v A4	$I_f=20\text{mA}$	60	$I_v(\text{ave.})^{(2)} \geq 120$		mcd

(1) Basically, wavelength uniformity is $\lambda_d \pm 5\text{nm}$.

(2) $I_v(\text{ave.})$ is the average luminous intensity of overall qualified chips from individual epiwafer.

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

NOTES:

1. UNITS: mil
2. WIRE BOND METALLIZATION: GOLD.
3. P SIDE UP ON WAFER.

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AlInGaP SUPER YELLOW LED CHIP.

CONFIDENTIAL INFORMATION

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RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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SCALE: N/A